

LVDS Interface ICs

# 27bit LVDS Transmitter

## BU90T81



● **General Description**

The BU90T81 transmitter operates from 20MHz to 112MHz wide clock range, and 27bits data of parallel LVCMOS level inputs(R/G/B24bits and VSYNC,HSYNC,DE) are converted to four channels of LVDS data stream. Data is transmitted seven times (7X) stream and reduce cable number by 3(1/3) or less.

The BU90T81 operates from a single 1.8V supply for low power. And the BU90T81 has low swing mode to be able to expect further low power and low EMI .

● **Features**

- 24bits data of parallel LVCMOS level inputs are converted to four channels of LVDS data stream.
- Support clock frequency from 20MHz up to 112MHz.
- Low power 1.8V CMOS design
- Power down mode
- Clock edge selectable
- Support 6bit/8bit mode selectable
- Support reduced swing LVDS for low EMI.
- Support LVDS Outputs pin reverse function
- Support spread spectrum clock generator input

● **Key Specifications**

- |                               |                |
|-------------------------------|----------------|
| ■ Supply Voltage range        | 1.65 to 1.95 V |
| ■ Operating frequency         | 20 to 112MHz   |
| ■ Operating Temperature Range | -20 to 85°C    |
| ■ Power Consumption           | 50mW(Typ)      |

● **Packages**

VBGA048W040 4.00 mm × 4.00 mm × 0.90 mm

● **Applications**

- Tablet
- Netbook PC
- Digital Picture Frame

● **Block Diagram**

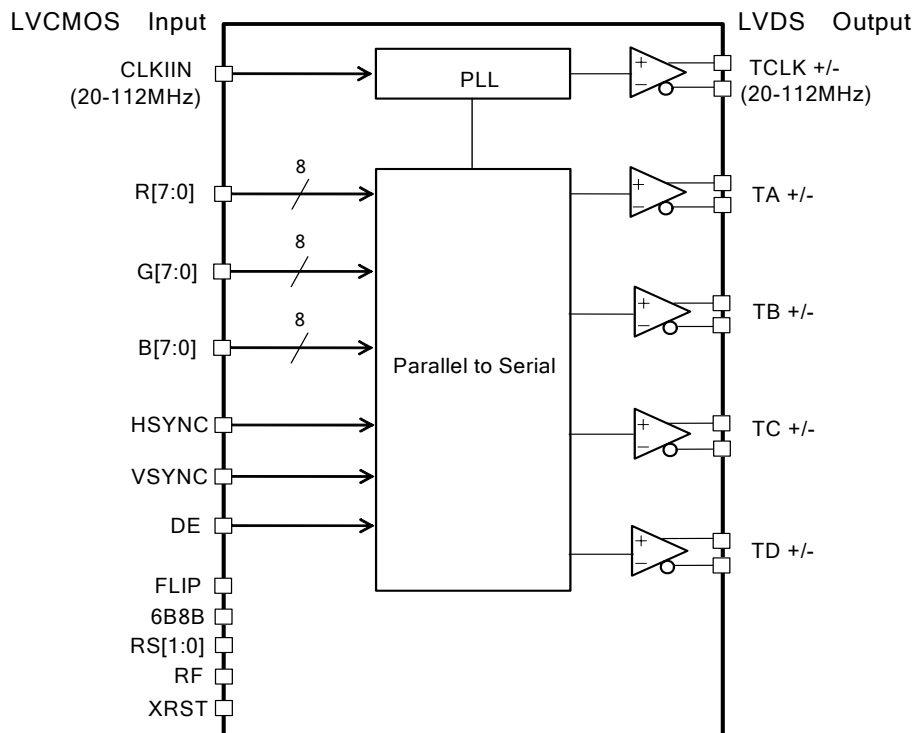


Figure-1 Block Diagram

○ Product structure : Silicon monolithic integrated circuit ○ This product is not designed protection against radioactive rays

## ● Pin Configuration

**Top view**

	1	2	3	4	5	6	7
A	G[5]	G[7]	R[1]	R[3]	R[5]	R[6]	R[7]
B	-	G[6]	R[0]	R[2]	R[4]	TA-	TA+
C	G[3]	G[4]	GND	RS[1]	RS[0]	TB-	TB+
D	G[1]	G[2]	RF	VDD	VDD	TC-	TC+
E	G[0]	B[7]	FLIP	6B8B	GND	TCLK-	TCLK+
F	B[6]	B[5]	B[2]	B[0]	DE	TD-	TD+
G	B[4]	B[3]	B[1]	HSYNC	VSYNC	CLKIN	XRST

### 48pin VBGA

Figure-2 Pin Diagram (Top View)

## ● Pin Description

Pin Name	Pin No.	Type	Descriptions															
TA+/-, TB+/-, TC+/-,TD+/-	B7,B6,C7,C6,D7,D6,F7,F6	LVDS OUT	LVDS Data out															
TCLK+/-	E7,6		LVDS Clock out															
R[7:0]	A7,A6,A5,B5,A4,B4,A3,B3	CMOS IN	Pixel and control data inputs															
G[7:0]	A2,B2,A1,C2,C1,D2,D1,E1																	
B[7:0]	E2,F1,F2,G1,G2,F3,G3,F4																	
HSYNC,VSYNC, DE	G4,G5,F5																	
CLKIN	G6			Clock input														
XRST	G7	CMOS IN	Power Down H : Normal operation L : Power down ( all LVDS output signal are Hi-z)															
RF	D3		Input CLK Triggering Edge Select. H : Rising edge L : Falling edge															
RS[1:0]	C3,C5		LVDS swing mode select <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th>RS1</th> <th>RS0</th> <th>LVDS swing</th> </tr> </thead> <tbody> <tr> <td>L</td> <td>L</td> <td>TYP=160mV</td> </tr> <tr> <td>L</td> <td>H</td> <td>TYP=200mV</td> </tr> <tr> <td>H</td> <td>L</td> <td>TYP=350mV</td> </tr> <tr> <td>H</td> <td>H</td> <td>Reserved</td> </tr> </tbody> </table>	RS1	RS0	LVDS swing	L	L	TYP=160mV	L	H	TYP=200mV	H	L	TYP=350mV	H	H	Reserved
RS1	RS0		LVDS swing															
L	L		TYP=160mV															
L	H	TYP=200mV																
H	L	TYP=350mV																
H	H	Reserved																
6B8B	E4	6bit/8bit mode select H : 6bit mode(FLIP=L TD+/- is Hiz) (FLIP=H TA+/- is Hiz) L : 8bit mode																
FLIP	E3	LVDS output pin reverse select. H : Reverse L : Normal																
VDD	D4,D5	POWER	1.8V Power supply															
GND	C3,E5	GND	Ground Pins															

### ● Absolute Maximum Ratings

Parameter	Symbol	Rating		Units
		Min	Max	
Supply Voltage	$V_{DD}$	-0.3	2.5	V
Input Voltage	$V_{IN}$	-0.3	$V_{DD}+0.3$	V
Output Voltage	$V_{OUT}$	-0.3	$V_{DD}+0.3$	V
Storage Temperature Range	Tstg	-55	125	°C

### ● Operating Ratings

Parameter	Symbol	Rating			Units	Conditions
		Min	Typ	Max		
Supply Voltage	$V_{DD}$	1.65	1.8	1.95	V	
Operating Temperature Range	Topr	-20	-	85	°C	
Operating frequency	Fmax	20	-	112	MHz	

### ● Package Power

Package	Power Dissipation (mW)	Derating (mW/°C)*1
VBGA048W040	800*1	8.0*1

\*1:Package power when mounting on the PCB board.

The size of PCB board : 114.3×76.2×1.6(mm<sup>3</sup>)  
 The material of PCB board : The FR4 glass epoxy board.

### ● DC characteristics

Table 1 : LVCMOS DC Specifications ( $V_{DD}=1.65V\sim 1.95V$ ,  $T_a=-20^{\circ}C\sim +85^{\circ}C$ )

Symbol	Parameter	Rating			Units	Conditions
		Min	Typ	Max		
$V_{IH}$	High Level Input Voltage	$V_{DD}\times 0.7$	-	$V_{DD}$	V	
$V_{IL}$	Low Level Input Voltage	GND	-	$V_{DD}\times 0.3$	V	
$I_{INC}$	Input Current	-10	-	+10	μA	$0V\leq V_{IN}\leq V_{DD}$

Table2: LVDS Transmitter DC Specifications ( $V_{DD}=1.65V\sim 1.95V$ ,  $T_a=-20^{\circ}C\sim +85^{\circ}C$ )

Symbol	Parameter	Rating			Units	Conditions
		Min	Typ	Max		
$V_{OD}$	Differential Output Voltage	250	350	450	mV	RL=100Ω RS[1:0]= HL RS[1:0]= LH RS[1:0]= LL
		130	200	270	mV	
		110	160	210	mV	
$\Delta V_{OD}$	Change in VOD between complementary output states	-	-	35	mV	RL=100Ω
$V_{OC}$	Common Mode Voltage	1.125	1.25	1.375	V	
$\Delta V_{OC}$	Change in VOC between complementary output states	-	-	35	mV	
$I_{OS}$	Output Short Circuit Current	-90	-	-	mA	$V_{OUT}=0V$
$I_{OZ}$	Output TRI-STATE Current	-10	-	+10	μA	XRST=0V, $V_{OUT}=0V$ to $V_{DD}$

● AC characteristics

Table 3 : Switching Characteristics (VDD=1.8V, Ta=25°C RL=100Ω CL=5pF RS[1:0]=HL)

Symbol	Parameter		Min	Typ	Max	Units
t <sub>TCP</sub>	CLK OUT Period		8.93	-	50	ns
t <sub>TCIT</sub>	CLK IN Transition time		-	-	5.0	ns
t <sub>TCH</sub>	CLK IN High Time		0.35t <sub>TCP</sub>	0.5t <sub>TCP</sub>	0.65t <sub>TCP</sub>	ns
t <sub>TCL</sub>	CLK IN Low Time		0.35t <sub>TCP</sub>	0.5t <sub>TCP</sub>	0.65t <sub>TCP</sub>	ns
t <sub>TS</sub>	LVSMOS Data Set up to CLK IN		2.5	-	-	ns
t <sub>TH</sub>	LVCMOS Data Hold from CLK IN		0	-	-	ns
t <sub>LVT</sub>	LVDS Transition Time		-	0.6	1.5	ns
T <sub>TSUP</sub>	Differential Output Set up Time	CLKOUT=112MHz	-	-	200	ps
T <sub>THLD</sub>	Differential Output Hold time	CLKOUT=112MHz	-	-	200	ps
t <sub>TOP6</sub>	Output Data Position 6		$2 \frac{t_{TCP}}{7} - T_{THLD}$	$2 \frac{t_{TCP}}{7}$	$2 \frac{t_{TCP}}{7} + T_{TSUP}$	ns
t <sub>TOP5</sub>	Output Data Position 5		$3 \frac{t_{TCP}}{7} - T_{THLD}$	$3 \frac{t_{TCP}}{7}$	$3 \frac{t_{TCP}}{7} + T_{TSUP}$	ns
t <sub>TOP4</sub>	Output Data Position 4		$4 \frac{t_{TCP}}{7} - T_{THLD}$	$4 \frac{t_{TCP}}{7}$	$4 \frac{t_{TCP}}{7} + T_{TSUP}$	ns
t <sub>TOP3</sub>	Output Data Position 3		$5 \frac{t_{TCP}}{7} - T_{THLD}$	$5 \frac{t_{TCP}}{7}$	$5 \frac{t_{TCP}}{7} + T_{TSUP}$	ns
t <sub>TOP2</sub>	Output Data Position 2		$6 \frac{t_{TCP}}{7} - T_{THLD}$	$6 \frac{t_{TCP}}{7}$	$6 \frac{t_{TCP}}{7} + T_{TSUP}$	ns
t <sub>TOP1</sub>	Output Data Position 1		$7 \frac{t_{TCP}}{7} - T_{THLD}$	$7 \frac{t_{TCP}}{7}$	$7 \frac{t_{TCP}}{7} + T_{TSUP}$	ns
t <sub>TOP0</sub>	Output Data Position 0		$8 \frac{t_{TCP}}{7} - T_{THLD}$	$8 \frac{t_{TCP}}{7}$	$8 \frac{t_{TCP}}{7} + T_{TSUP}$	ns
t <sub>TPLL</sub>	Phase Locked Loop Set Time		-	-	10	ms

● AC Timing Diagrams

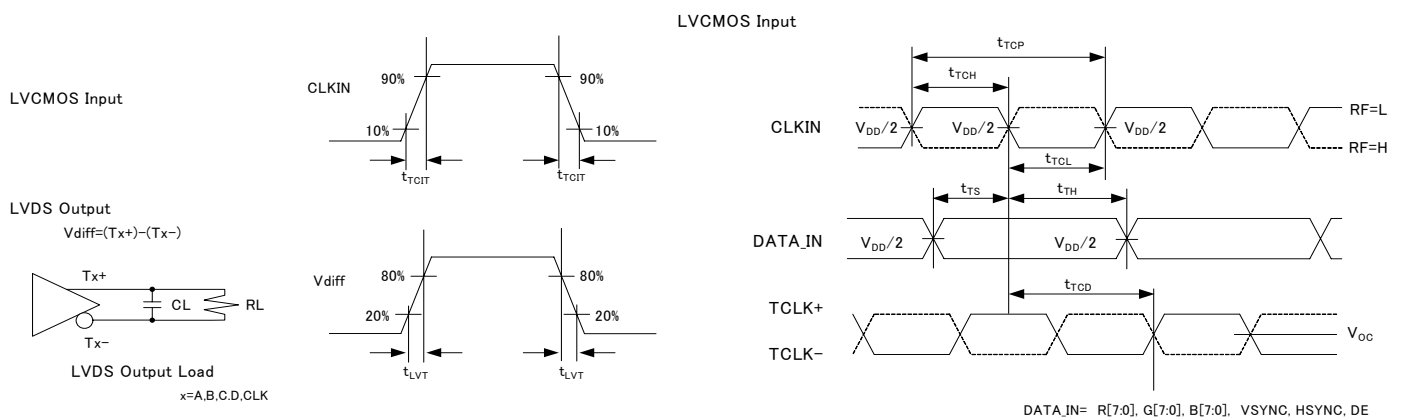


Figure-3 LVCMOS Input AC Timing Diagrams

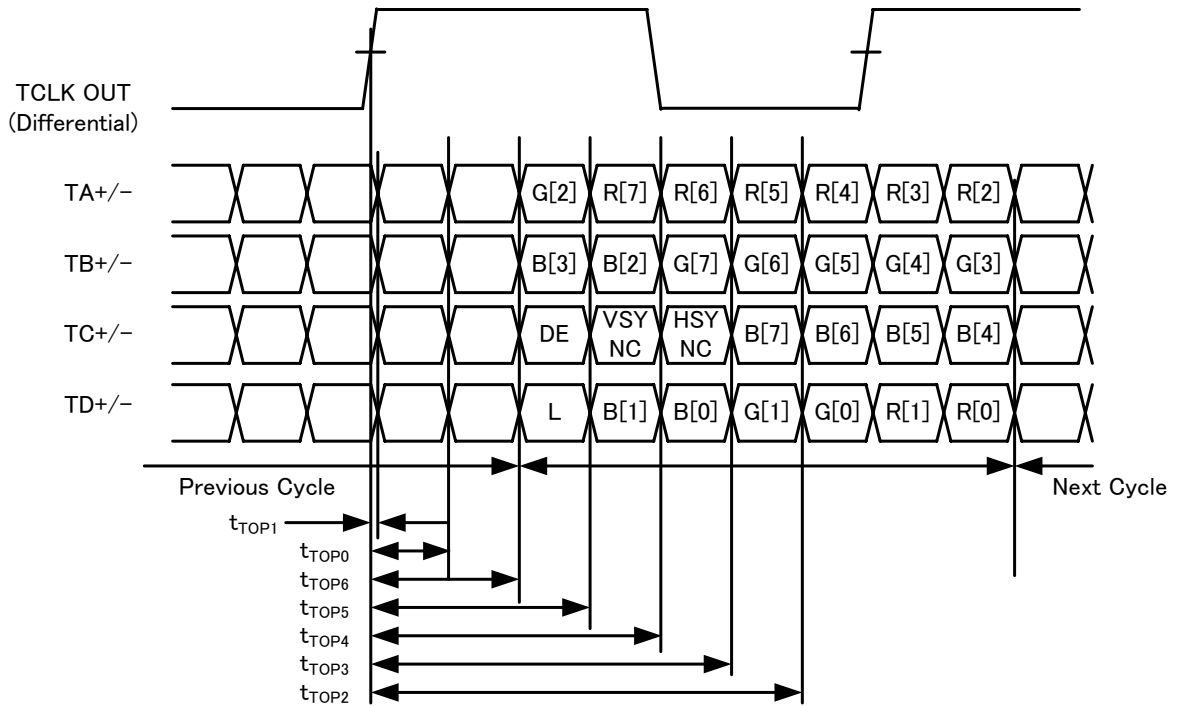


Figure-4 LVDS Output AC Timing Diagrams

● Phase Locked Loop Set Time

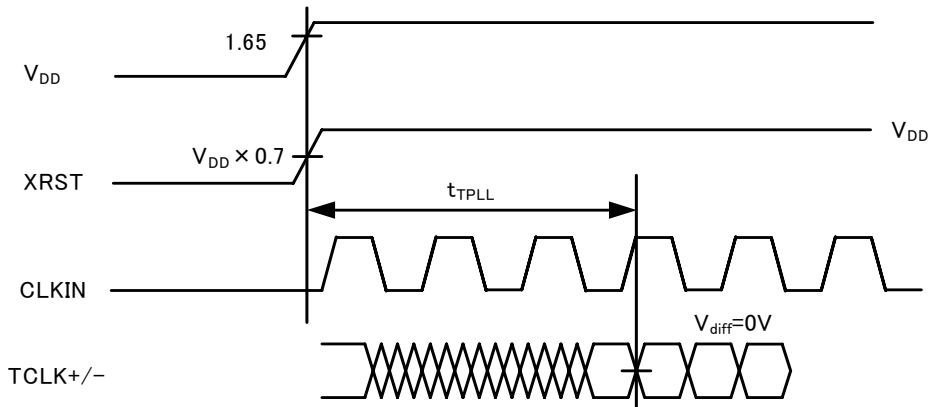


Figure-5 Phase Locked Loop Set Time

●Supply Current

Table 4: Supply Current (6B8B = L)

Symbol	Parameter	Rating			Units	Conditions	
		Min	Typ	Max			
I <sub>TCCG</sub>	Transmitter Supply Current	-	30.4	-	mA	RL=100Ω, CL=5pF VDD=1.8V, RS[1:0]=HL Gray Scale Pattern	f=85MHz
		-	22.5	-	mA	RL=100Ω, CL=5pF VDD=1.8V, RS[1:0]=LH Gray Scale Pattern	f=85MHz
		-	20.4	-	mA	RL=100Ω, CL=5pF VDD=1.8V, RS[1:0]=LL Gray Scale Pattern	f=85MHz
I <sub>TCCW</sub>	Transmitter Supply Current	-	32.4	-	mA	RL=100Ω, CL=5pF VDD=1.8V, RS[1:0]=HL Worst case Pattern	f=85MHz
		-	24.5	-	mA	RL=100Ω, CL=5pF VDD=1.8V, RS[1:0]=LH Worst case Pattern	f=85MHz
		-	22.4	-	mA	RL=100Ω, CL=5pF VDD=1.8V, RS[1:0]=LL Worst case Pattern	f=85MHz
I <sub>TCCS</sub>	Transmitter Power Down Supply Current	-	-	10	μA	XRST=L	

Gray Scale Pattern

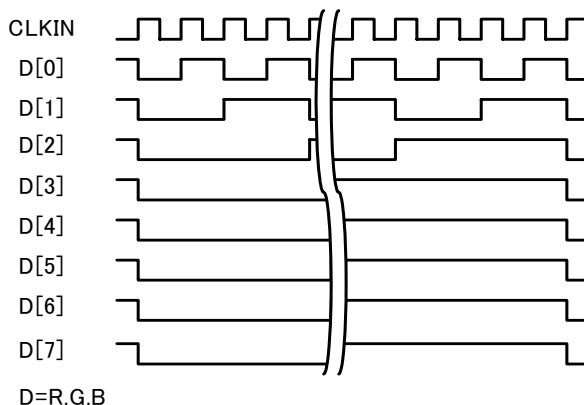


Figure -6 Gray Scale Pattern

Worst Case Pattern (Maximum Power condition)

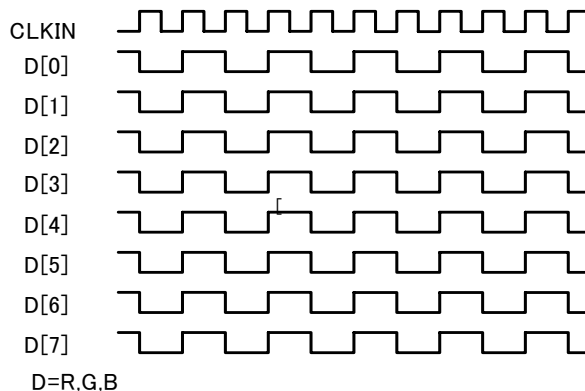
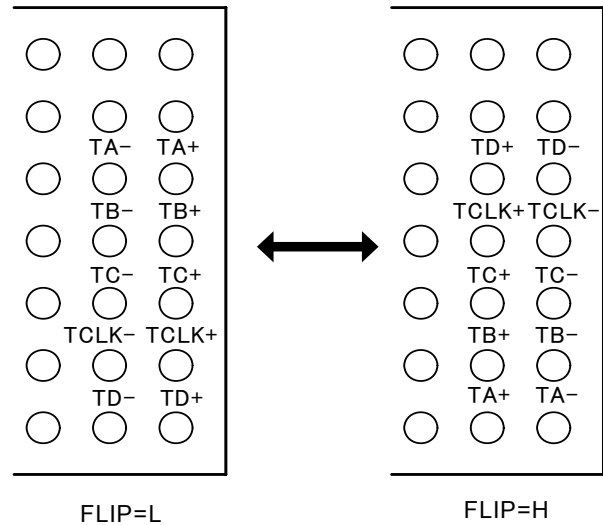


Figure -7 Worst Case Pattern

●LVDS Data Output Table for Function of FLIP pin

Table 5: LVDS Data Output Pin Name

Pin No	Output Pin Names	
	FLIP=L	FLIP=H
B7	TA+	TD-
B6	TA-	TD+
C7	TB+	TCLK-
C6	TB-	TCLK+
D7	TC+	TC-
D6	TC-	TC+
E7	TCLK+	TB-
E6	TCLK-	TB+
F7	TD+	TA-
F6	TD-	TA+



●LVCMOS Data Inputs Pixel Map Table

Table 6: LVCMOS Data Inputs Pixel Map Table

	TFT Panel Data		BU90T81 Input
	24Bit	18Bit	
LSB	R0	-	R0
	R1	-	R0
	R2	R0	R1
	R3	R1	R2
	R4	R2	R3
	R5	R3	R4
	R6	R4	R5
MSB	R7	R5	R6
LSB	G0	-	R7
	G1	-	G0
	G2	G0	G1
	G3	G1	G2
	G4	G2	G3
	G5	G3	G4
	G6	G4	G5
MSB	G7	G5	G6
LSB	B0	-	G7
	B1	-	B0
	B2	B0	B1
	B3	B1	B2
	B4	B2	B3
	B5	B3	B4
	B6	B4	B5
MSB	B7	B5	B6
	VSYNC	VSYNC	B7
	HSYNC	HSYNC	HSYNC
	DE	DE	DE

●LVDS Output Data Mapping

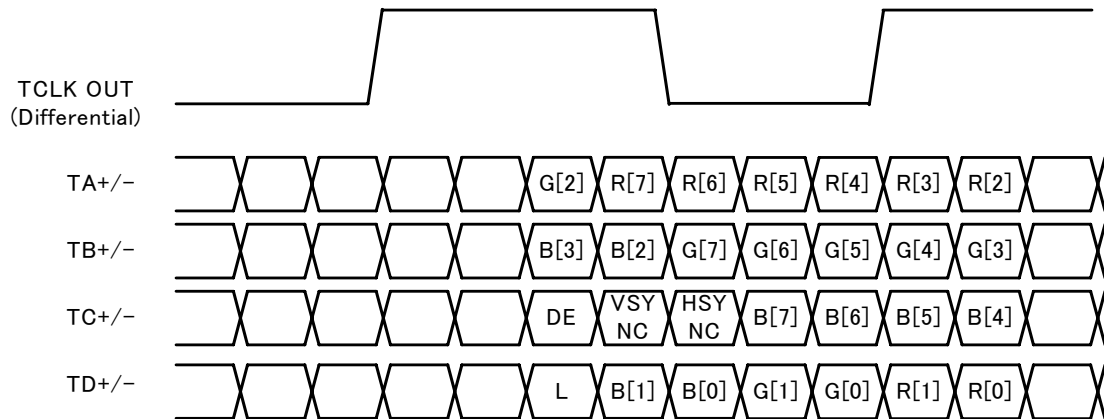


Figure-8 LVDS output mapping (6B8B=L, FLIP=L)

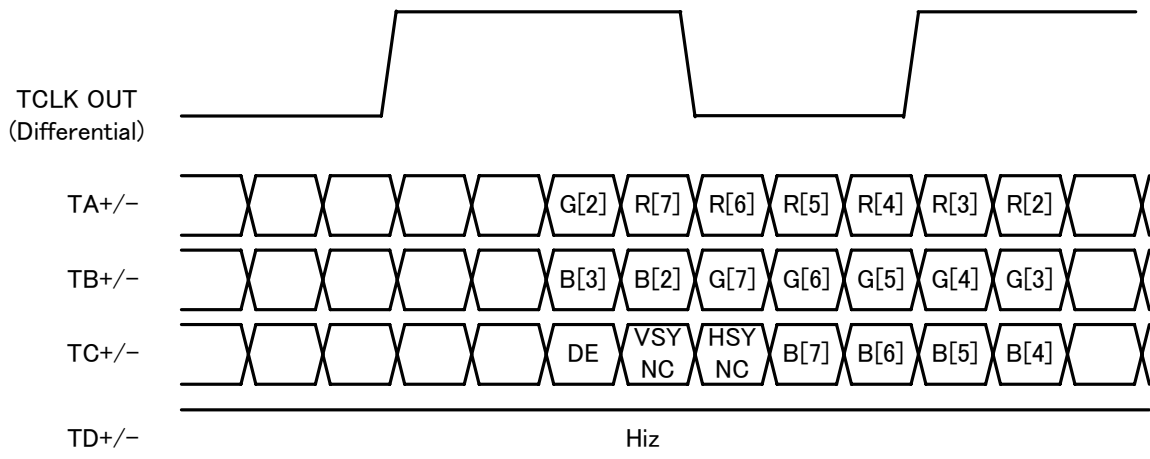


Figure-9 LVDS output mapping (6B8B=H, FLIP=L)



● Typical Application Circuit ( 24bit mode)

Example

BU90T81: LVCMOS Data Input /rising edge/200mV swing output/normal output mapping

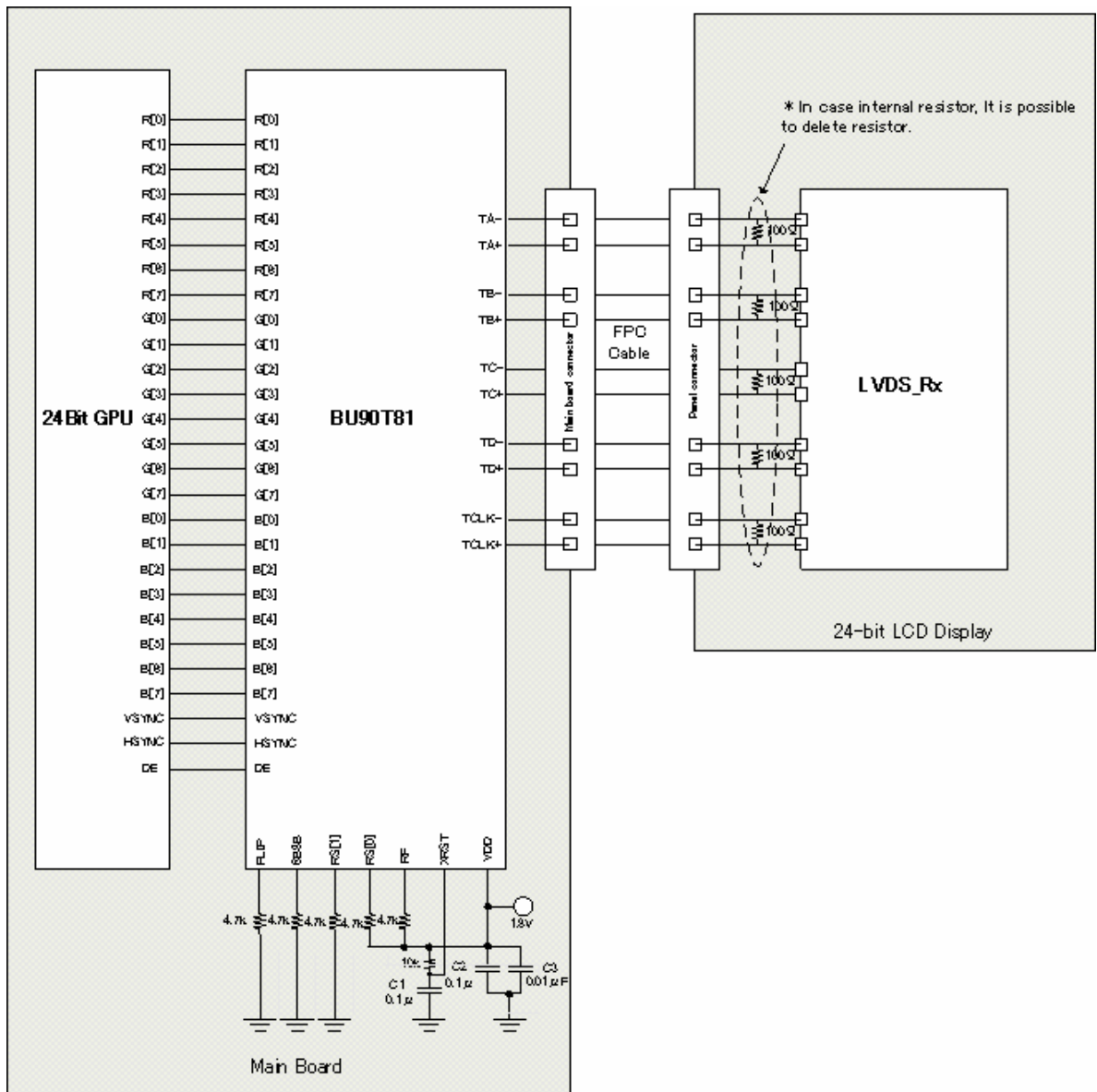


Figure-10 Application Circuit (24bit mode)

● Typical Application Circuit ( 18bit mode)

Example

BU90T81: LVCMOS Data Input /rising edge/200mV swing output/normal output mapping

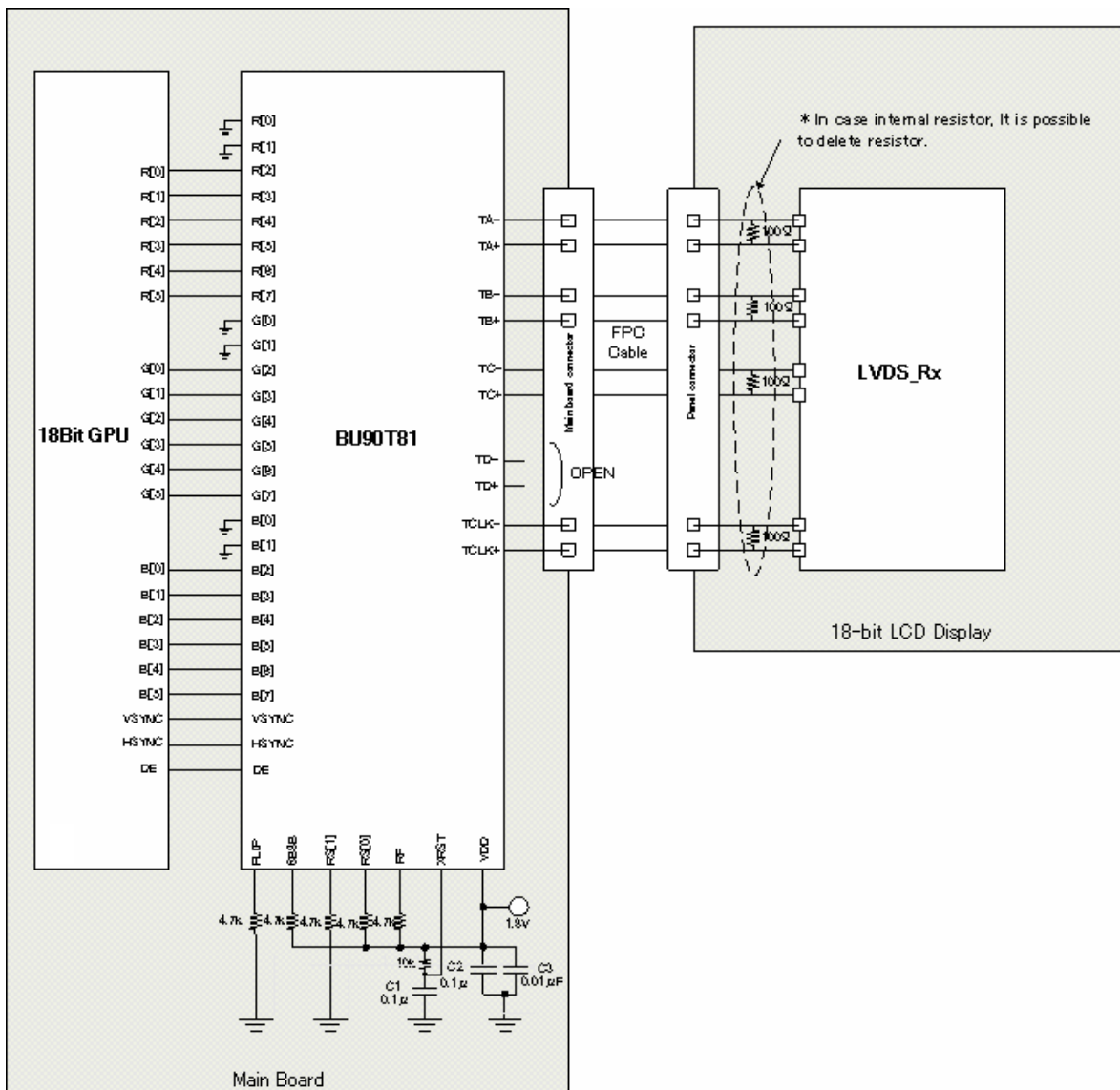


Figure-11 Application Circuit (18bit mode)

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